

ON Semiconductor®

ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3 / ISL9V3040S3

EcoSPARK® 300mJ, 400V, N-Channel Ignition IGBT

General Description

The ISL9V3040D3S, ISL9V3040S3S, ISL9V3040P3, and ISL9V3040S3 are the next generation ignition IGBTs that offer outstanding SCIS capability in the space saving D-Pak (TO-252), as well as the industry standard D²-Pak (TO-263), and TO-262 and TO-220 plastic packages. This device is intended for use in automotive ignition circuits, specifically as a coil driver. Internal diodes provide voltage clamping without the need for external components.

EcoSPARK® devices can be custom made to specific clamp voltages. Contact your nearest On Semiconductor sales office for more information.

Formerly Developmental Type 49362

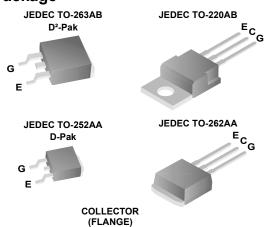
Applications

- · Automotive Ignition Coil Driver Circuits
- · Coil- On Plug Applications

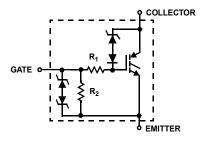
Features

- · Space saving D-Pak package availability
- SCIS Energy = 300mJ at T_J = 25°C
- · Logic Level Gate Drive

Package



Symbol



Device Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
BV _{CER}	Collector to Emitter Breakdown Voltage (I _C = 1 mA)	430		
BV _{ECS}	Emitter to Collector Voltage - Reverse Battery Condition (I _C = 10 mA)	24	V	
E _{SCIS25}	At Starting T_J = 25°C, I_{SCIS} = 14.2A, L = 3.0 mHy	300	mJ	
E _{SCIS150}	At Starting T _J = 150°C, I _{SCIS} = 10.6A, L = 3.0 mHy	170	mJ	
I _{C25}	Collector Current Continuous, At T _C = 25°C, See Fig 9	21	Α	
I _{C110}	Collector Current Continuous, At T _C = 110°C, See Fig 9	17	Α	
V_{GEM}	Gate to Emitter Voltage Continuous	±10	V	
P_{D}	Power Dissipation Total T _C = 25°C	150	W	
	Power Dissipation Derating T _C > 25°C	1.0	W/°C	
TJ	Operating Junction Temperature Range	-40 to 175	°C	
T _{STG}	Storage Junction Temperature Range	-40 to 175	°C	
TL	Max Lead Temp for Soldering (Leads at 1.6mm from Case for 10s)	300	°C	
T _{pkg}	Max Lead Temp for Soldering (Package Body for 10s)	260	°C	
ESD	Electrostatic Discharge Voltage at 100pF, 1500Ω	4	kV	

Package	Mark	ing and Ordering	g Inf	ormatio	n						
Device Marking		Device	P	ackage		Reel Size	Таре	Tape Width		Quantity	
V3040	0D	ISL9V3040D3ST	TO	D-252AA		330mm	16	3mm	2	500	
V3040S ISL9V3040S3ST		T	D-263AB		330mm	24mm		800			
V3040P ISL9V3040P3 T0		O-220AB Tube		N/A		50					
		O-262AA Tube		N/A		50					
		O-252AA Tube		N/A		75					
			O-263AB Tube			N/A		50			
Electrica	al Cha	racteristics T _A = 25	s°C un	less otherwis	e no	ted					
Symbol		Parameter		Test Conditions			Min	Тур	Max	Units	
Off State (Charact	eristics									
BV _{CER}	Collector to Emitter Breakdown Voltage			I_C = 2mA, V_{GE} = 0, R_G = 1K Ω , See Fig. 15 T_A = -40 to 150°C			370	400	430	V	
BV _{CES}	Collector to Emitter Breakdown Voltage			I _C = 10mA, V _{GE} = 0, R _G = 0, See Fig. 15 T _J = -40 to 150°C			390	420	450	V	
BV _{ECS}	Emitter to Collector Breakdown Voltage			$I_C = -75\text{mA}, V_{GE} = 0V,$ $T_C = 25^{\circ}\text{C}$			30	-	-	V	
BV _{GES}	Gate to I	Gate to Emitter Breakdown Voltage		I _{GES} = ± 2mA			±12	±14	-	V	
I _{CER}	Collector to Emitter Leakage Current			V _{CER} = 250		T _C = 25°C	-	-	25	μΑ	
	, and the second			$R_G = 1KΩ$, See Fig. 11		T _C = 150°C	-	-	1	mA	
I _{ECS}	Emitter to Collector Leakage Current			V _{EC} = 24V, See Fig. 11		T _C = 25°C	-	-	1	mA	
200						T _C = 150°C	-	-	40	mA	
R ₁	Series Gate Resistance					-	70	-	Ω		
R ₂ Gate to Emitter Resistance							10K	-	26K	Ω	
On State (Charact	eristics									
V _{CE(SAT)}	Collector	collector to Emitter Saturation Voltage				T _C = 25°C, See Fig. 3	-	1.25	1.60	V	
V _{CE(SAT)}	Collector	Collector to Emitter Saturation Voltage		I _C = 10A, V _{GE} = 4.5V	_C = 10A, T		-	1.58	1.80	V	
V _{CE(SAT)}	Collector	Collector to Emitter Saturation Voltage		I _C = 15A, V _{GE} = 4.5V T _C = 150°C		T _C = 150°C	-	1.90	2.20	V	
Dynamic (Charact	eristics									
Q _{G(ON)}	Gate Charge			I _C = 10A, V _{CE} = 12V,			-	17	-	nC	
				V _{GE} = 5V, See Fig. 14							
V _{GE(TH)}	Gate to Emitter Threshold Voltage				$T_C = 25^{\circ}C$ $T_C = 150^{\circ}C$	1.3 0.75	-	2.2 1.8	V		
				See Fig. 10		ŭ	0.73		1.0		
V _{GEP}		Emitter Plateau Voltage		$I_C = 10A, V_C$	E =	12V	-	3.0	-	V	
Switching	Charac	cteristics									
$t_{d(ON)R}$	Current	Turn-On Delay Time-Resis	stive	V _{CE} = 14V, F	$R_{G} = 1K\Omega$		_	0.7	4	μs	
t_{rR}	Current	Rise Time-Resistive		$V_{GE} = 5V, R_{J} = 25^{\circ}C, S$			-	2.1	7	μs	
t _{d(OFF)L}	Current	Turn-Off Delay Time-Induc	tive	V _{CE} = 300V,	, L = 500µHy,		-	4.8	15	μs	
t _{fL}	Current	Fall Time-Inductive		$V_{GE} = 5V, R$ $T_{J} = 25^{\circ}C, S$			-	2.8	15	μs	
SCIS	Self Clamped Inductive Switching			T_J = 25°C, L = 3.0 mHy, R_G = 1K Ω , V_{GE} = 5V, See Fig. 1 & 2			-	-	300	mJ	
Thermal C	haracte	eristics									
$R_{\theta JC}$	Thormal	Resistance Junction-Case	2	All packages			_	_	1.0	°C/W	

Typical Performance Curves

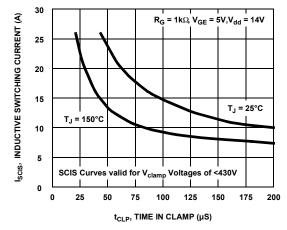


Figure 1. Self Clamped Inductive Switching Current vs Time in Clamp

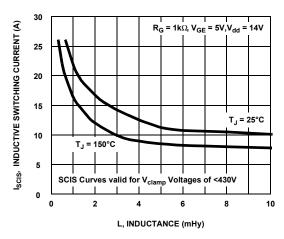


Figure 2. Self Clamped Inductive Switching Current vs Inductance

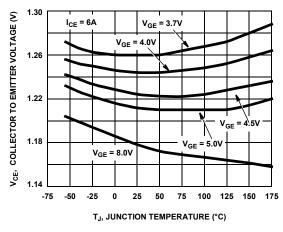


Figure 3. Collector to Emitter On-State Voltage vs Junction Temperature

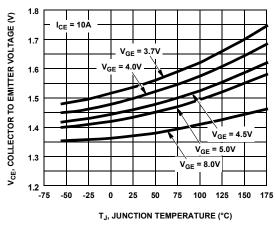


Figure 4. Collector to Emitter On-State Voltage vs Junction Temperature

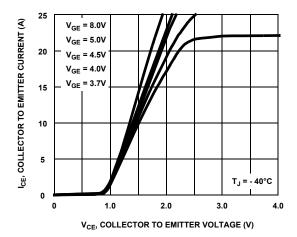


Figure 5. Collector to Emitter On-State Voltage vs Collector Current

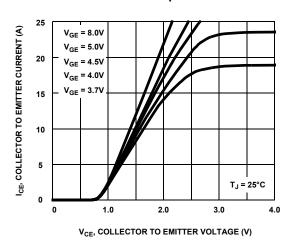


Figure 6. Collector to Emitter On-State Voltage vs Collector Current

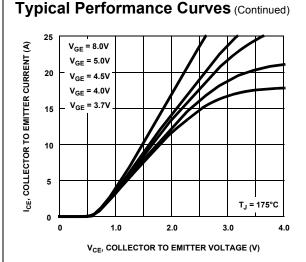


Figure 7. Collector to Emitter On-State Voltage vs Collector Current

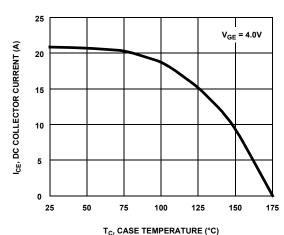


Figure 9. DC Collector Current vs Case Temperature

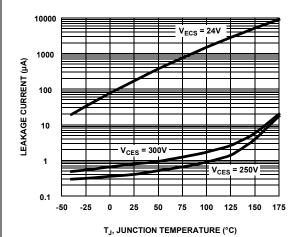


Figure 11. Leakage Current vs Junction Temperature

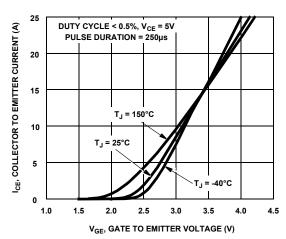


Figure 8. Transfer Characteristics

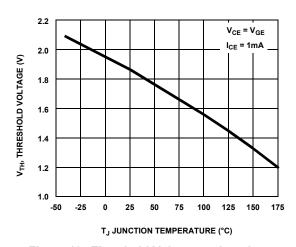


Figure 10. Threshold Voltage vs Junction Temperature

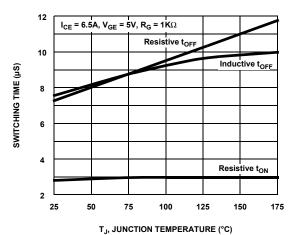
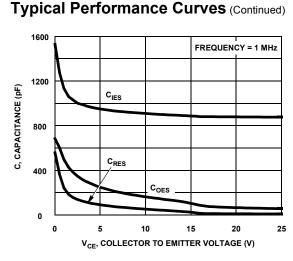


Figure 12. Switching Time vs Junction Temperature



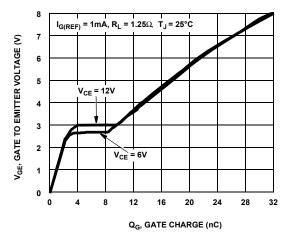


Figure 13. Capacitance vs Collector to Emitter Voltage

Figure 14. Gate Charge

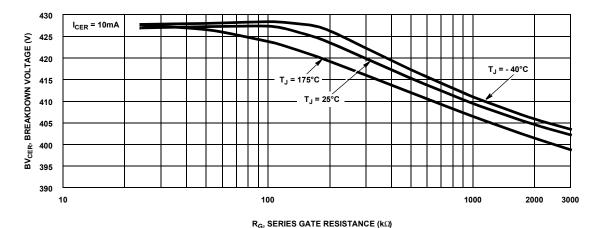


Figure 15. Breakdown Voltage vs Series Gate Resistance

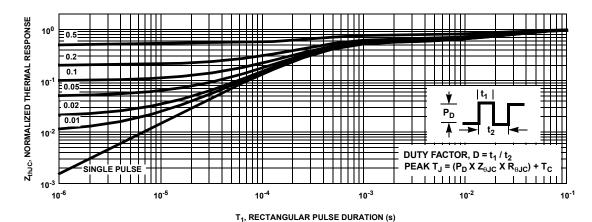


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

Test Circuit and Waveforms

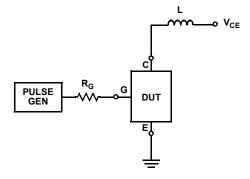


Figure 17. Inductive Switching Test Circuit

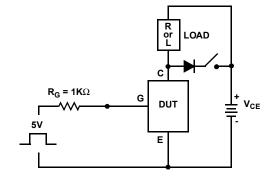


Figure 18. t_{ON} and t_{OFF} Switching Test Circuit

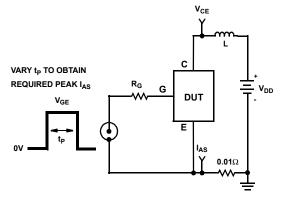


Figure 19. Energy Test Circuit

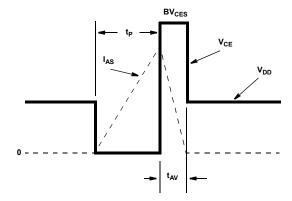


Figure 20. Energy Waveforms

SPICE Thermal Model REV 7 March 2002 JUNCTION ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3 / ISL9V3040S3 CTHERM1 th 6 2.1e -3 CTHERM2 6 5 1.4e -1 CTHERM3 5 4 7.3e -3 CTHERM4 4 3 2.1e -1 RTHERM1 CTHERM1 CTHERM5 3 2 1.1e -1 CTHERM6 2 tl 6.2e +6 RTHERM1 th 6 1.2e -1 6 RTHERM2 6 5 1.9e -1 RTHERM3 5 4 2.2e -1 RTHERM4 4 3 6.0e -2 RTHERM2 CTHERM2 RTHERM5 3 2 5.8e -2 RTHERM6 2 tl 1.6e -3 SABER Thermal Model 5 SABER thermal model ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3 / ISL9V3040S3 RTHERM3 CTHERM3 template thermal_model th tl thermal_c th, tl 4 ctherm.ctherm1 th 6 = 2.1e - 3ctherm.ctherm2 6 5 = 1.4e -1 ctherm.ctherm3 5 4 = 7.3e -3 ctherm.ctherm4 4 3 = 2.2e -1 RTHERM4 CTHERM4 ctherm.ctherm5 3 2 =1.1e -1 ctherm.ctherm6 2 tl = 6.2e +6 rtherm.rtherm1 th 6 = 1.2e -1 3 rtherm.rtherm2 6 5 = 1.9e - 1rtherm.rtherm3 5 4 = 2.2e -1 rtherm.rtherm4 4 3 = 6.0e -2 RTHERM5 CTHERM5 rtherm.rtherm5 3 2 = 5.8e -2 rtherm.rtherm6 2 tl = 1.6e -3 2 RTHERM6 CTHERM6 CASE

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